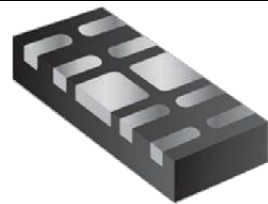


MATERIAL DECLARATION SHEET

BOURNS®

Material Number	CDDFN10-3324P			
Product Line	Semiconductor Products			
Compliance Date	2025/2/12			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.106200	Silicon	7440-21-3	100.00%	2.72%	2.72%
2	Lead Frame	Copper alloy	1.337751	Copper	7440-50-8	95.30%	34.30%	35.99%
			0.035095	Iron	7439-89-6	2.50%	0.90%	
			0.001404	Phosphorus	7723-14-0	0.10%	0.04%	
			0.001404	Zinc	7440-66-6	0.10%	0.04%	
			0.028076	Silver	7440-22-4	1.99%	0.71%	
			0.000070	Lead	7439-92-1	0.01%	0.00%	
3	Epoxy	Polymer	0.090000	Silicon dioxide	7631-86-9	60.00%	2.32%	3.85%
			0.022500	Modified Epoxy Resin	Proprietary	15.00%	0.58%	

MATERIAL DECLARATION SHEET

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			0.015000	Poly[oxy[(2-oxiranyl)-1,2-cyclohexanediyl]], a-hydroxy-, ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1)	244772-00-7	10.00%	0.38%	
			0.015000	Phenol-formaldehyde polymer	9003-35-4	10.00%	0.38%	
			0.007500	Reaction product: bisphenol-A-(epichlorhydrin); epoxy resin (number average molecular weight <= 700)	25068-38-6	5.00%	0.19%	
4	Gold Wire	Noble metal	0.169983	Gold	7440-57-5	99.99%	4.36%	4.36%
			0.000017	Others	/	0.01%	0.00%	
5	Mold Compound	Polymer	0.009500	Epoxy Resin 1	Trade secret	0.50%	0.24%	48.72%
			0.009500	Epoxy Resin 2	Trade secret	0.50%	0.24%	
			0.009500	Epoxy Resin 3	Trade secret	0.50%	0.24%	

MATERIAL DECLARATION SHEET



			0.038000	Hardener	Trade secret	2.00%	0.97%	
			0.000950	Organic Phosphorus Compounds	Trade secret	0.05%	0.02%	
			0.003800	Carbon black	1333-86-4	0.20%	0.10%	
			1.735650	Amorphous silica1	60676-86-0	91.35%	44.51%	
			0.093100	Amorphous silica2	14808-60-7	4.90%	2.40%	
6	Plating	plating	0.169983	Tin	7440-31-5	99.99%	4.36%	4.36%
			0.000009	Others	/	0.01%	0.00%	
		Total weight	3.9 mg					

This Document was updated on: 2025/2/12